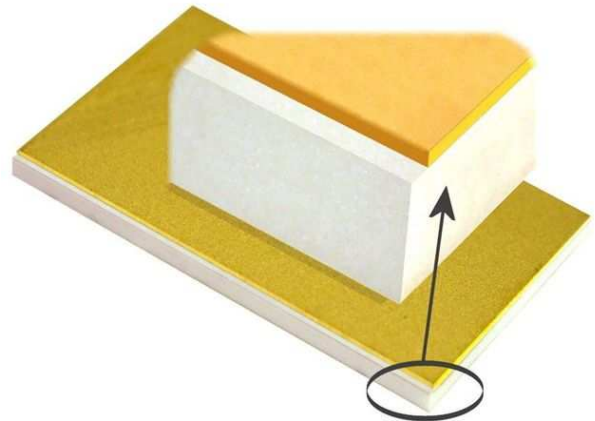


FOR IMMEDIATE RELEASE**Remtec Introduces Submounts with Zero Pullback™ Metallization for High Power Laser Diodes**

Norwood, MA. November 7, 2007. Remtec Inc., a leader in custom and semi-standard ceramic packaging based on Plated Copper on Thick & Thin Film (PCTF[®]) technology, has introduced new, high performance submounts with Zero Pullback metallization of 50 micron thick copper on BeO and AlN for high power laser diodes.

Remtec's new high performance laser diode submounts offer 25-75 micron thick copper metallization and a unique Zero Pullback™ from a burr free ceramic edge for various demanding optoelectronic applications. A Zero Pullback metallization with a burr free edge greatly enhances performance characteristics of edge emitting diodes. In addition, plated copper up to 75 micron permits elevated power levels. Submount materials include BeO with thermal conductivity from 280 W/m²K to 325 W/m²K and AlN from 170 W/m²K to 230 W/m²K.



PCTF[®] technology combines elements of thick and thin films with plated copper and nickel/gold finish. Therefore, substrates are available with multiple metallization techniques and selective plating options permitting both silver thick film and TiW thin film seed layers, plated copper from 5 to 75 micron and Ni-Au finish with gold thickness from .1 to 2.5 micron. This selective plating capability ensures excellent wettability of GaAs dice by gold tin soldering. Ceramic and copper surface finish can be held to less than 1 μm. Overall submount thickness tolerances can be held to +/- 13 μm, flatness to 1 μm and surface roughness to less than Ra .05 μm.

Other features of PCTF submounts are three and four-sided metallization, plugged via holes and excellent wire bondability and solderability. PCTF technology, with its ductile structure of plated copper over thick or thin film on ceramic, also minimizes solder joint stresses during assembly of Ga-As devices to ceramic substrates. In addition, by varying copper thickness on AlN ceramics, a better TCE matching can be achieved thus eliminating a cracking of large size dice.

Remtec's laser diode submounts are compatible with all standard interconnect assembly techniques used for laser diodes and photodiodes. Low upfront tooling costs and fast turnaround time permit designers to bring their systems into production faster and with lower engineering costs.

Remtec, a RoHS compliant and ISO 9001:2000 registered company, provides ceramic packaging solutions for optoelectronics, microwave / RF components and modules and power electronics. Applications include high performance laser and photo diodes submounts, optoelectronics circuits, spacers, power modules as well as RF power amplifiers and TC modules. Additional data are available at www.remtec.com.